What is claimed is:

1. A method for electrostatically applying a powder adhesive formulation to a non-metallic substrate comprising:

a) forming a powder adhesive composition comprising a polymer:

b) applying an electrostatic charge to the powder;

c) depositing the charged powder onto a non-metallic substrate,

wherein the electrostatically-applied adhesive is capable of being reactivated and used as an adhesive.

2. The method of claim 1 wherein said polymer is a natural polymer, a synthetic polymer, or a mixture thereof.

3. The method of claim 1 wherein said polymer comprises cationic functionality.

4. The method of claim1 wherein said substrate is selected from the group consisting of wood, glass, paper, leather, paperboard, card board, corrugated board, cellulose, plastics, wovens, and non-woven materials.

5. A method for bonding a non-metallic substrate to another substrate comprising:

a) forming a powder adhesive formulation comprising a polymer:

b) applying an electrostatic charge to the powder adhesive formulation;

c) depositing the charged powder onto a non-metallic substrate, activating said powder adhesive formulation, and contacting the activated adhesive-containing non-metallic substrate with a second substrate;

d) allowing the adhesive between the two substrates to cure, producing bonded substrates.

6. The method of claim 5 wherein the steps of step c) are performed in the order of activating the powder adhesive at the same time as it is being deposited onto a non-metallic substrate, then contacting the activated adhesive-containing non-metallic substrate to a second substrate.

7. The method of claim 5 wherein the steps of step c) are performed in the order of depositing the charged powder onto a non-metallic substrate, contacting the adhesive-containing non-

metallic substrate to a second substrate, then activating said powder adhesive formulation.

8. The method of claim 5 wherein said second substrate is a non-metallic substrate.

9. The method of claim 5 wherein said second substrate is a metallic substrate.

10. The method of claim 5 wherein said activation of the powder adhesive comprises contacting the adhesive with a water mist, heat, or radiation.

11. A powder adhesive coated non-metallic substrate comprising a non-metallic substrate having directly deposited thereon by electrostatic forces, a powder adhesive capable of being activated to exhibit adhesive properties.